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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











#### 0.4W SURFACE MOUNT PRECISION ZENER DIODE

### **Features**

- 400mW Power Dissipation on FR-4 PCB
- Very Tight Tolerance on Vz
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

- Case: SOD323F
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Alloy leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.01 grams (Approximate)

#### SOD323F



Top View

### Ordering Information (Note 4)

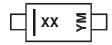
Part Number	Case	Packaging		
(Type Number)-7*	SOD323F	3,000/Tape & Reel		

<sup>\*</sup> Example: The part number for the 3.6 Volt device would be D3Z3V6BF-7.

Notes

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



XX = Product Type Marking Code (See Electrical Characteristics Table) YM = Date Code Marking Y = Year (ex: X = 2010)

M = Month (ex: 9 = September)

#### Date Code Key

Year	201	0	2011	2012	2013	2014	2015	201	6 20	017	2018	2019	2020
Code	X		Υ	Z	Α	В	С	D		E	F	G	Н
Month		Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Forward Voltage	@ $I_F = 10mA$	V <sub>F</sub>	0.9	V

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_{D}$	400	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ hetaJA}$	312.5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

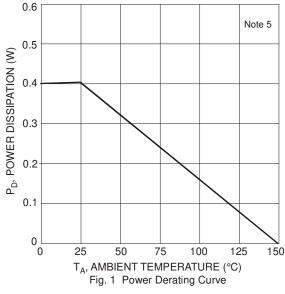
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

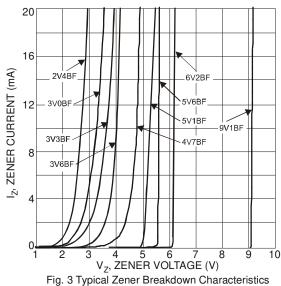
Туре	Marking		oltage Rar Note 6)	nge	ge Maximum Zener Impedance f = 1kHz			Maximum Reverse Current (Note 7)		Typical Temperature Coefficient	Typical Total Capacitance
Number	Code $V_Z @ I_{ZT}$ $I_{ZT}$ $Z_{ZT} @ I_{ZT}$ $Z_{ZK} @ I_{ZK}$		I <sub>ZK</sub>	I <sub>R</sub>	@ V <sub>R</sub>	@ I <sub>ZT</sub> = 5mA	@ V <sub>R</sub> = 0V, f = 1MHz				
		Min (V)	Max (V)	mΑ	2	Ω	mA	μА	٧	mV/°C	pF
D3Z2V4BF	L0	2.43	2.63	5	100	1000	0.5	50	1	-1.6	215
D3Z2V7BF	L1	2.69	2.91	5	100	1000	0.5	20	1	-1.7	205
D3Z3V0BF	L2	2.85	3.07	5	95	1000	0.5	10	1	-1.7	195
D3Z3V3BF	L3	3.32	3.53	5	95	1000	0.5	5	1	-1.9	145
D3Z3V6BF	L4	3.60	3.85	5	90	500	1.0	5	1	-2.4	185
D3Z3V9BF	L5	3.89	4.16	5	90	500	1.0	3	1	-2.5	175
D3Z4V3BF	L6	4.17	4.48	5	90	600	1.0	3	1	-2.5	165
D3Z4V7BF	L7	4.55	4.75	5	90	600	1.0	2	1	-1.1	150
D3Z5V1BF	GM, L8	4.96	5.20	5	60	250	0.5	2	1.5	0.3	145
D3Z5V6BF	L9	5.48	5.73	5	50	100	0.5	1	2.5	1.7	20
D3Z6V2BF	LA	6.06	6.33	5	50	80	0.5	0.5	3	2.5	95
D3Z6V8BF	LB	6.65	6.93	5	40	60	0.5	0.5	3.5	3.4	82
D3Z7V5BF	LC	7.28	7.60	5	10	60	0.5	0.5	4	4.0	70
D3Z8V2BF	LD	8.02	8.36	5	10	60	0.5	0.5	5	4.6	57
D3Z9V1BF	LE	8.85	9.23	5	10	60	0.5	0.5	6	5.0	50
D3Z10BF	LF	9.77	10.21	5	10	60	0.5	0.1	7	6.1	45
D3Z11BF	LG	10.78	11.22	5	10	60	0.5	0.1	8	7.4	41
D3Z12BF	LH	11.74	12.24	5	10	80	0.5	0.1	9	8.2	36
D3Z13BF	LJ	12.91	13.49	5	10	80	0.5	0.1	10	9.4	33
D3Z15BF	LK	14.34	14.98	5	15	80	0.5	0.05	11	12.1	28
D3Z16BF	LL	15.85	16.51	5	20	80	0.5	0.05	12	13.7	25
D3Z18BF	LM	17.56	18.35	5	20	80	0.5	0.05	13	15.8	24
D3Z20BF	LN	19.52	20.39	5	20	100	0.5	0.05	15	16.4	22
D3Z22BF	LP	21.54	22.47	5	25	100	0.5	0.05	17	18.4	20
D3Z24BF	LQ	23.72	24.78	5	30	120	0.5	0.05	19	20.4	18
D3Z27BF	LR	26.19	27.53	5	40	150	0.5	0.05	21	18.0	17
D3Z30BF	LS	29.19	30.69	5	40	200	0.5	0.05	23	28.6	17
D3Z33BF	LT	32.15	33.79	5	40	250	0.5	0.05	25	32.2	15
D3Z36BF	LU	35.07	36.87	5	60	300	0.5	0.05	27	34.9	14

Notes:

- 5. Device mounted on FR-4 PCB with suggested pad layout, board size 35mm \* 25mm.
  6. The Zener voltage is measured <40ms after power is supplied.</li>
  7. Short duration pulse test used to minimize self-heating effect.







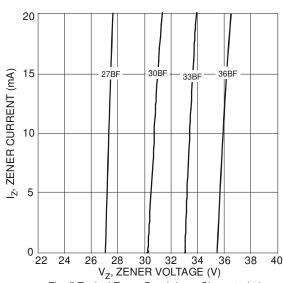
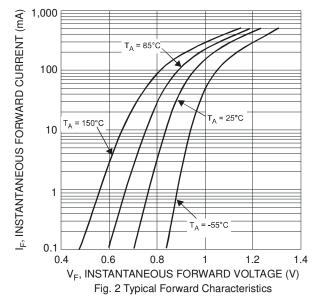


Fig. 5 Typical Zener Breakdown Characteristics



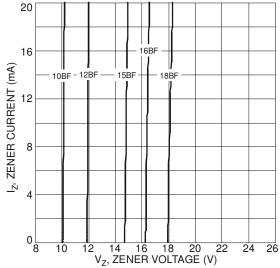


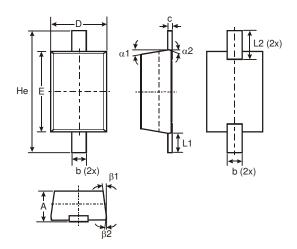
Fig. 4 Typical Zener Breakdown Characteristics



## **Package Outline Dimensions**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

### SOD323F

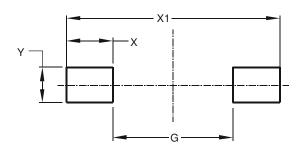


SOD323F							
Dim	Min	Max	Тур				
Α	0.60	0.75	-				
b	0.25	0.35	-				
С	0.05	0.26	-				
D	1.15	1.35	1.25				
Е	1.60	1.80	1.70				
He	2.30	2.70	2.50				
L1	0.30	0.50	0.40				
L2	0.41	0.61	0.51				
α1	_	_	7°				
α2	_	-	3°				
β1	-	-	7°				
β2	β2 –		3°				
All I	All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

### SOD323F



Dimensions	Value (in mm)
G	1.280
Х	0.710
X1	2.700
Υ	0.403



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